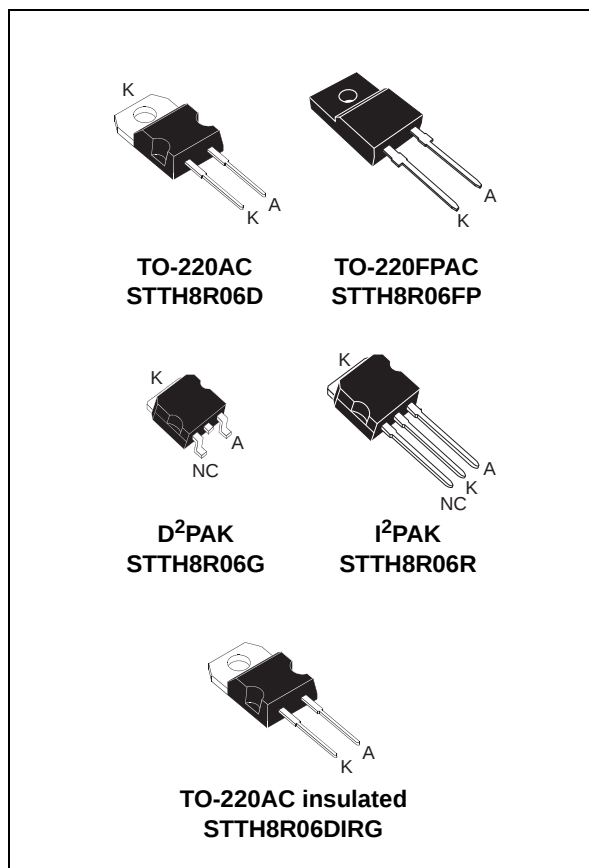


Turbo 2 ultrafast high voltage rectifier

Datasheet - production data



Description

The STTH8R06, which uses ST Turbo 2 600 V technology, is specially suited as boost diode in continuous mode power factor corrections and hard switching conditions.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	8 A
V_{RRM}	600 V
I_{RM} (typ)	5.5 A
T_j	175 °C
V_F (typ)	1.4 V
t_{rr} (max)	25 ns

Features

- Ultrafast switching
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses
- Package insulation voltage:
 - TO-220AC Ins: 2500 V rms
 - TO-220FPAC: 2000 V DC

1 Characteristics

Table 2. Absolute ratings (limiting values)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		600	V
$I_{F(RMS)}$	Forward current rms	TO-220AC / TO-220FPAC / D ² PAK / I ² PAK	30	A
		TO-220AC ins.	24	
$I_{F(AV)}$	Average forward current $\delta = 0.5$	TO-220AC / D ² PAK / I ² PAK	8	A
		TO-220FPAC		
		TO-220AC ins.		
I_{FSM}	Surge non repetitive forward current		$t_p = 10$ ms sinusoidal	A
T_{stg}	Storage temperature range		-65 to + 175	°C
T_j	Maximum operating junction temperature		175	°C

Table 3. Thermal resistance

Symbol	Parameter		Value (max)	Unit
$R_{th(j-c)}$	Junction to case	TO-220AC / D ² PAK / I ² PAK	2.2	°C/W
		TO-220FPAC	4.6	
		TO-220AC ins.	3.8	

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I_R	Reverse leakage current	$T_j = 25$ °C	$V_R = V_{RRM}$			30	μ A
		$T_j = 125$ °C			35	400	
V_F	Forward voltage drop	$T_j = 25$ °C	$I_F = 8$ A			2.9	V
		$T_j = 125$ °C			1.4	1.8	

To evaluate the conduction losses use the following equation: $P = 1.16 \times I_{F(AV)} + 0.08 I_{F(RMS)}^2$

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$T_j = 25$ °C	$I_F = 0.5$ A, $I_{rr} = 0.25$ A, $I_R = 1$ A			25	ns
			$I_F = 1$ A, $dI_F/dt = -50$ A/ μ s, $V_R = 30$ V			45	

Table 5. Dynamic characteristics

I_{RM}	Reverse recovery current	$T_j = 125\text{ }^{\circ}\text{C}$	$I_F = 8\text{ A}$, $V_R = 400\text{ V}$, $dI_F/dt = -200\text{ A}/\mu\text{s}$		5.5	7.2	A
S factor	Softness factor				0.3		
Q_{rr}	Reverse recovery charges				150		nC
t_{fr}	Forward recovery time	$T_j = 25\text{ }^{\circ}\text{C}$	$I_F = 8\text{ A}$, $dI_F/dt = 64\text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$			150	ns
V_{FP}	Forward recovery voltage					5	V

Figure 1. Conduction losses versus average current

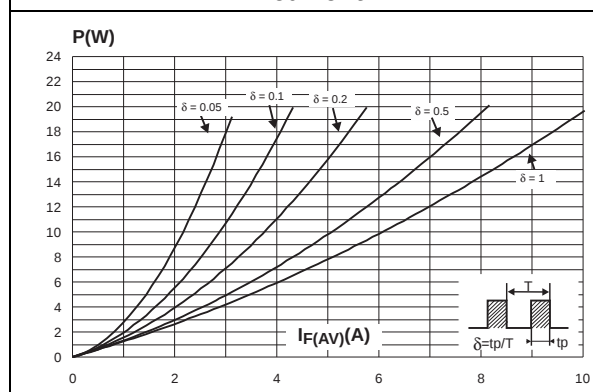


Figure 2. Forward voltage drop versus forward current

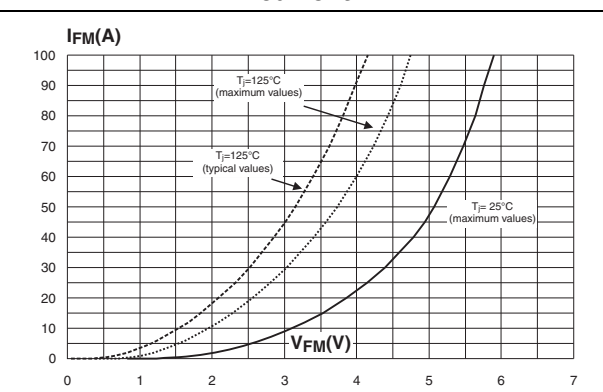


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

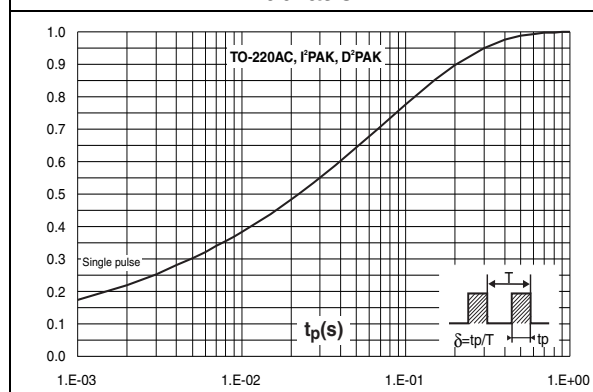


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

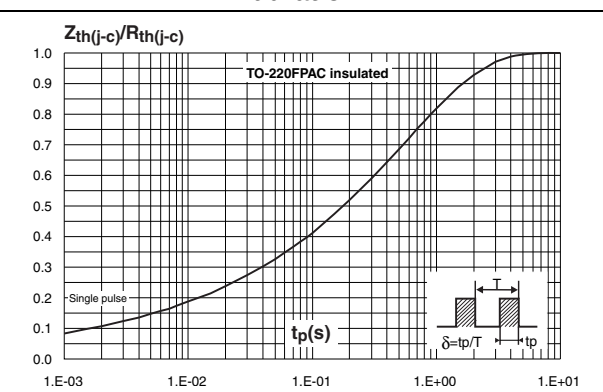


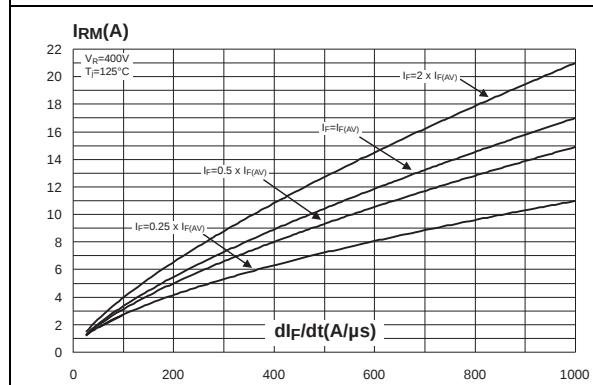
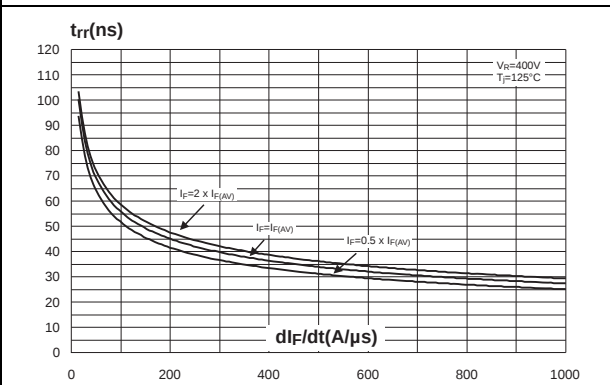
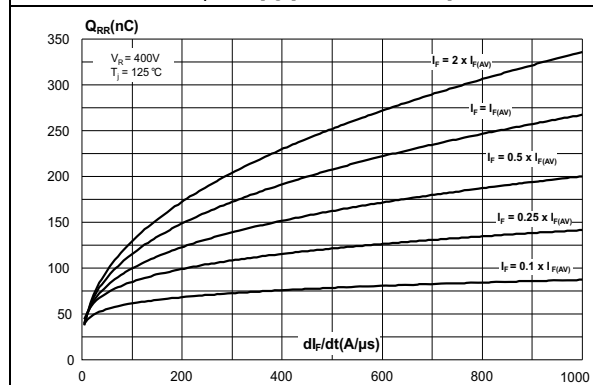
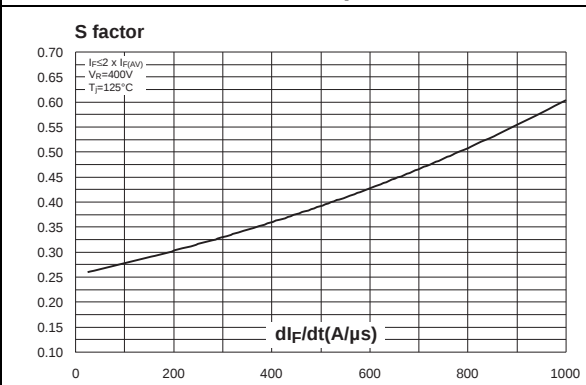
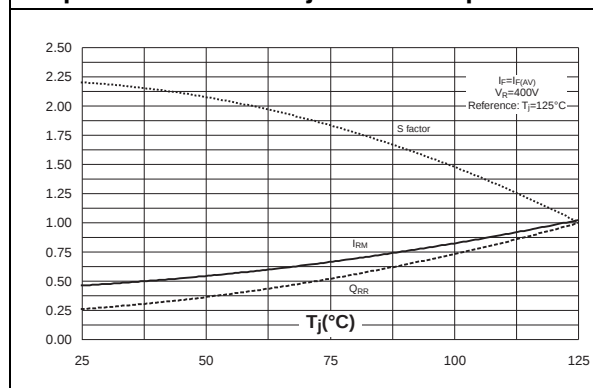
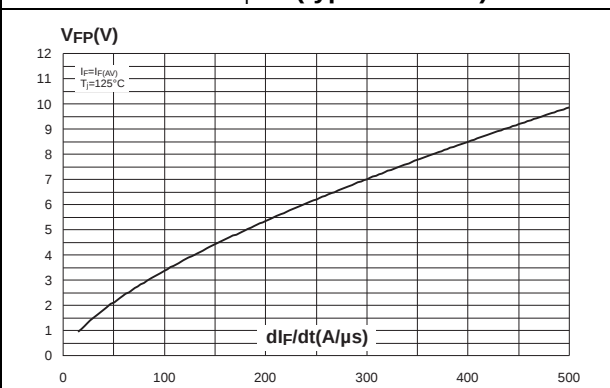
Figure 5. Peak reverse recovery current versus di_F/dt (typical values)**Figure 6. Reverse recovery time versus di_F/dt (typical values)****Figure 7. Reverse recovery charges versus di_F/dt (typical values)****Figure 8. Softness factor versus di_F/dt (typical values)****Figure 9. Relative variations of dynamic parameters versus junction temperature****Figure 10. Transient peak forward voltage versus di_F/dt (typical values)**

Figure 11. Forward recovery time versus di_F/dt (typical values)

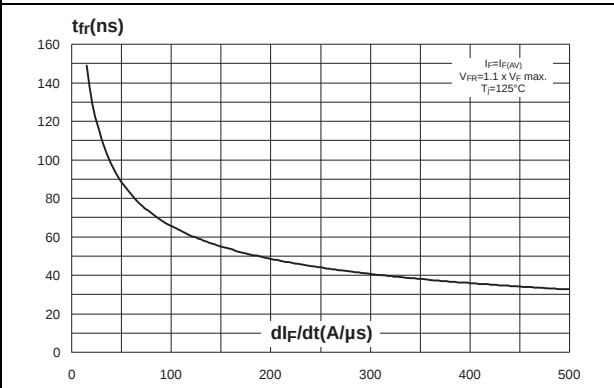


Figure 12. Junction capacitance versus reverse voltage applied (typical values)

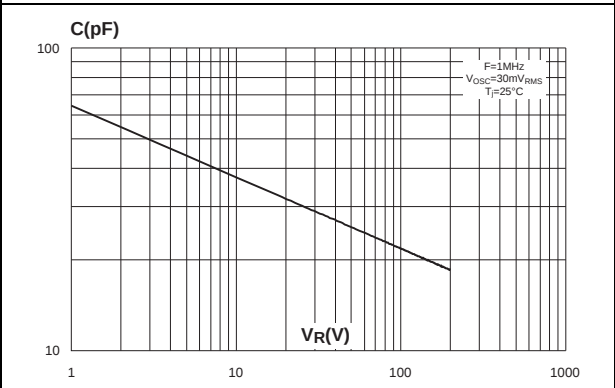
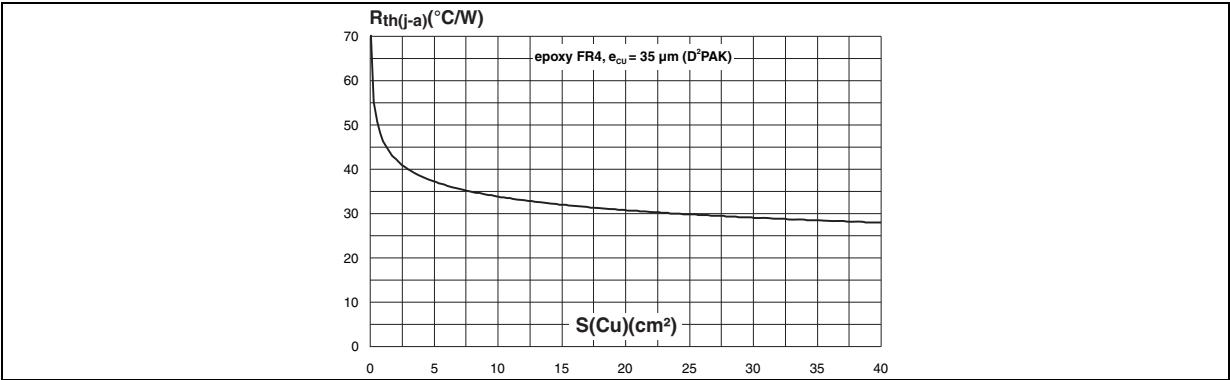


Figure 13. Thermal resistance junction to ambient versus copper surface under tab



2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque values:
 - 0.8 to 1.0 N·m (TO-220FPAC),
 - 0.4 to 0.6 N·m (TO-220AC)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Figure 14. TO-220AC dimension definitions

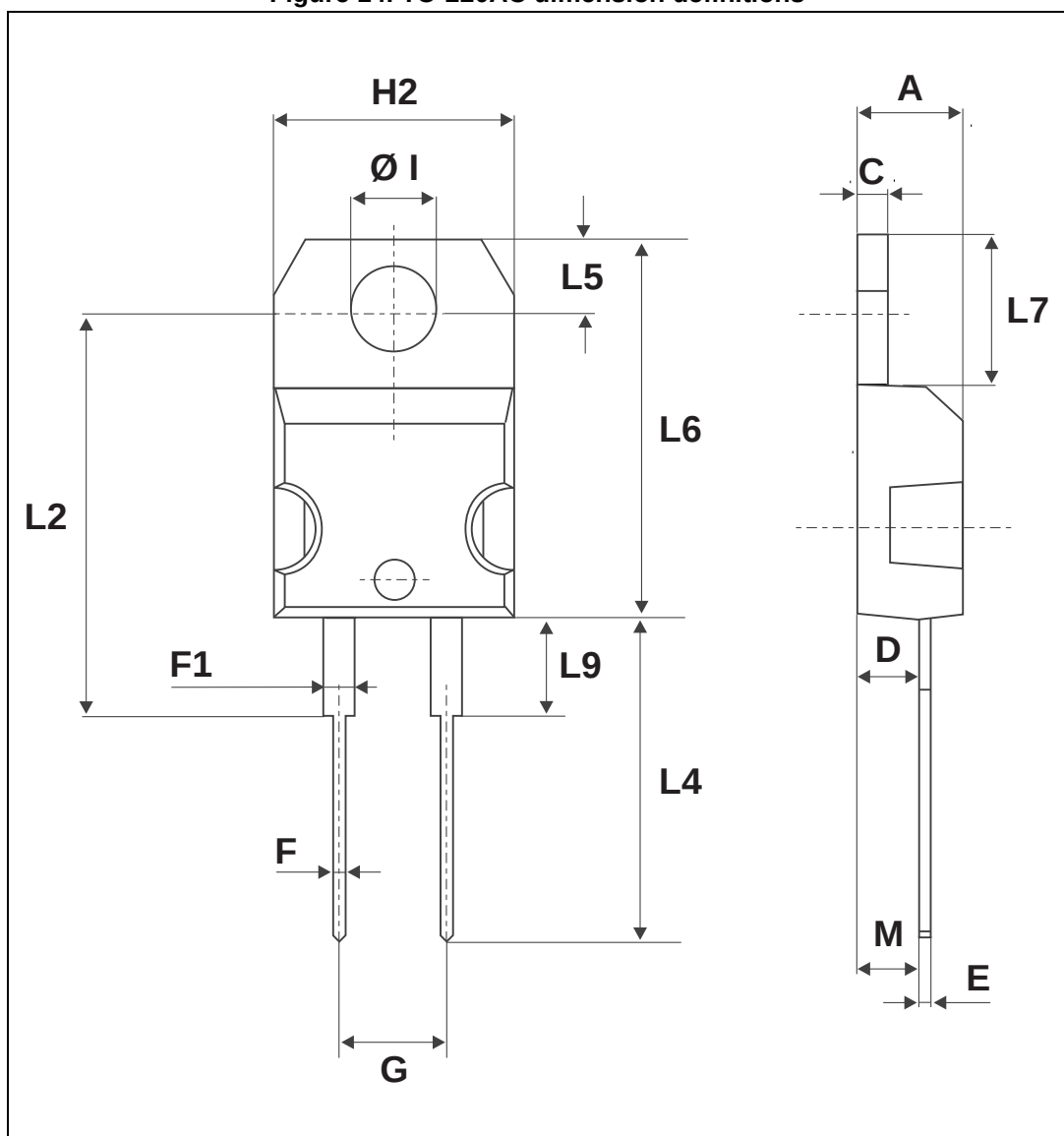


Table 6. TO-220AC dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
C	1.23		1.32	0.048		0.051
D	2.40		2.72	0.094		0.107
E	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.066
G	4.95		5.15	0.194		0.202
H2	10.00		10.40	0.393		0.409
L2		16.40 typ.			0.645 typ.	
L4	13.00		14.00	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.20		6.60	0.244		0.259
L9	3.50		3.93	0.137		0.154
M		2.6 typ.			0.102 typ.	
Diam. I	3.75		3.85	0.147		0.151

Figure 15. TO-220FPAC dimension definitions

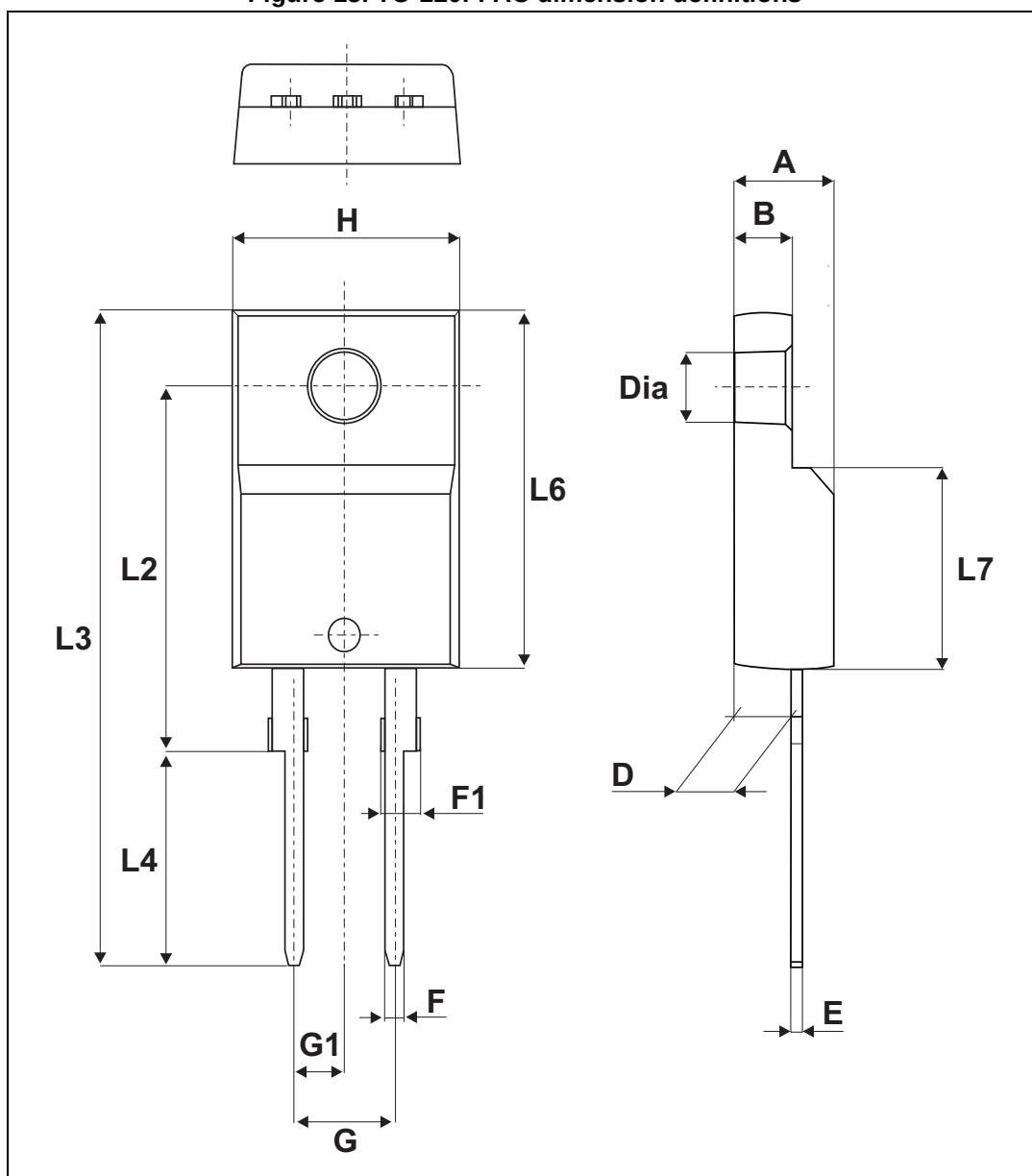


Table 7. TO-220FPAC dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.70	0.018		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.70	0.045		0.067
G	4.95		5.20	0.195		0.205
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2		16 Typ.			0.63 Typ.	
L3	28.6		30.6	1.126		1.205
L4	9.8		10.6	0.386		0.417
L6	15.9		16.4	0.626		0.646
L7	9.00		9.30	0.354		0.366
Dia.	3.00		3.20	0.118		0.126

Figure 16. TO-220AC (NIns. & Ins. 20-up) dimension definitions

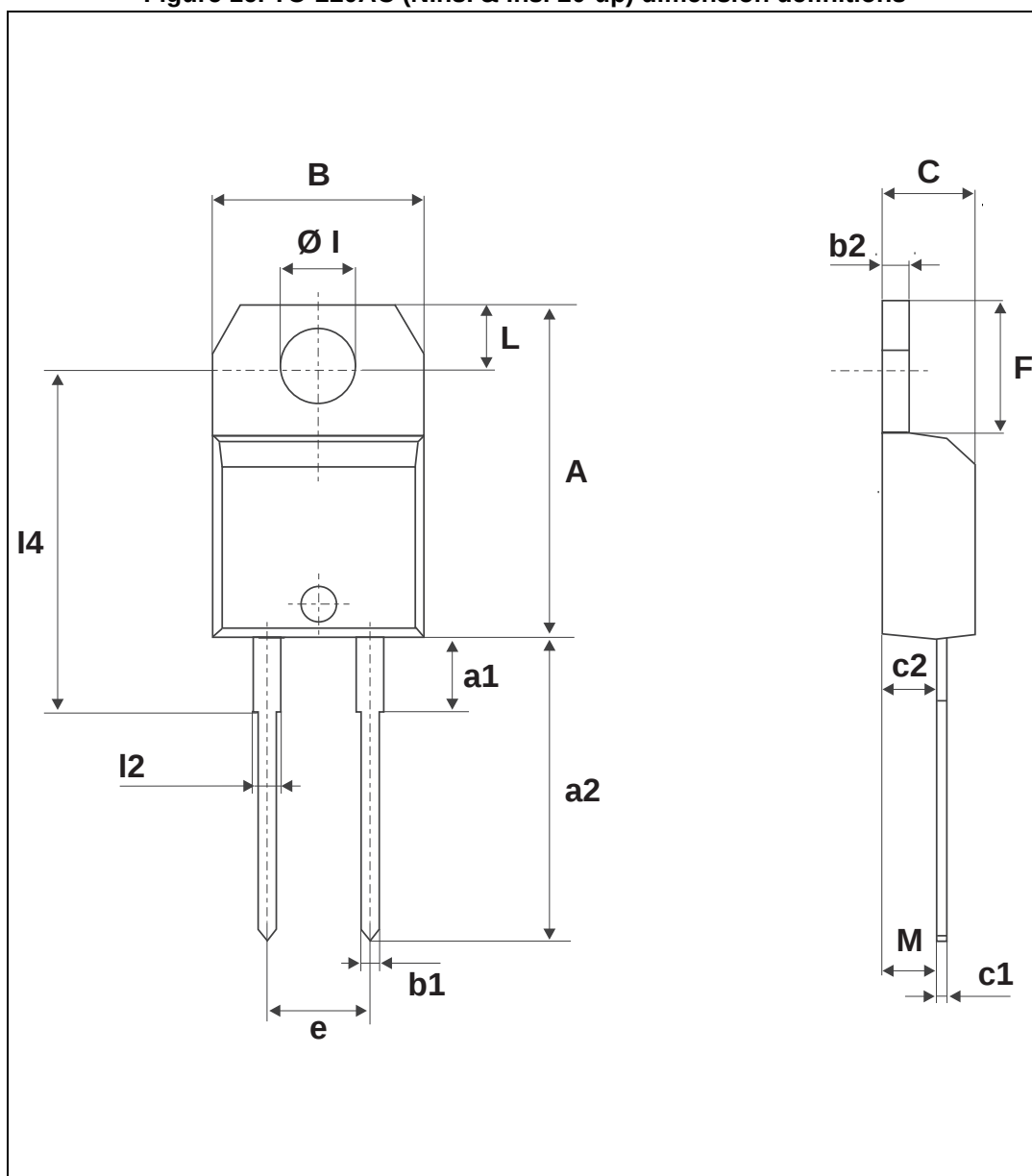


Table 8. TO-220AC (NIns. & Ins. 20-up) dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.20		15.90	0.598		0.625
a1		3.75			0.147	
a2	13.00		14.00	0.511		0.551
B	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
C	4.40		4.60	0.173		0.181
c1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
e	4.80		5.40	0.189		0.212
F	6.20		6.60	0.244		0.259
ØI	3.75		3.85	0.147		0.151
l4	15.80	16.40	16.80	0.622	0.646	0.661
L	2.65		2.95	0.104		0.116
l2	1.14		1.70	0.044		0.066
M		2.60			0.102	

Devices in I²PAK with nickel-plated back frame must NOT be mounted by frame soldering like SMDs. Such devices are intended to be through-hole mounted ONLY and in no circumstances shall ST be held liable for any lack of performance or damage arising out of soldering of nickel-plated back frames.

Figure 17. I²PAK dimension definitions

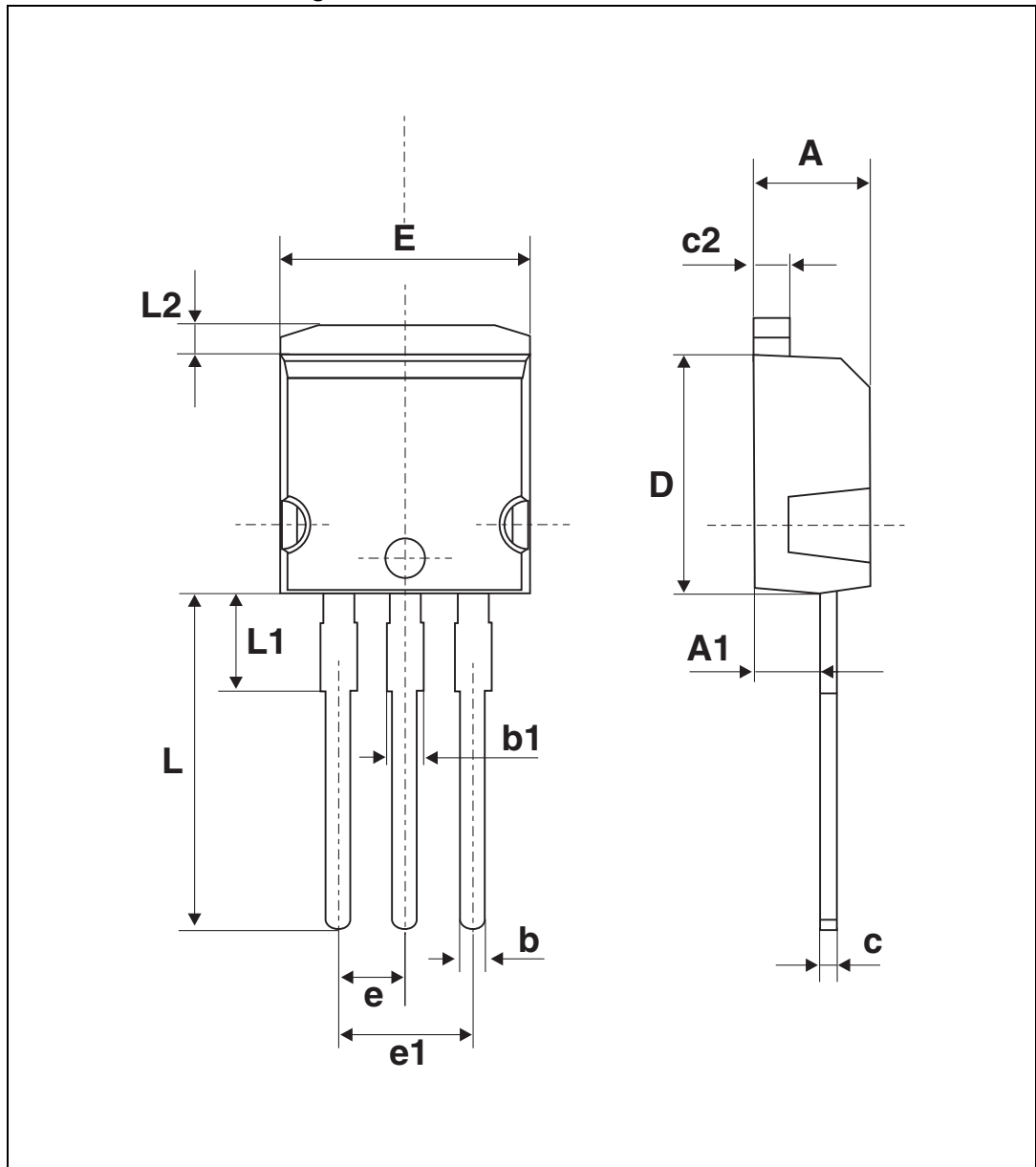


Table 9. I²PAK dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
A1	2.40		2.72	0.094		0.107
b	0.61		0.88	0.024		0.035
b1	1.14		1.70	0.044		0.067
c	0.49		0.70	0.019		0.028
c2	1.23		1.32	0.048		0.052
D	8.95		9.35	0.352		0.368
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.195		0.203
E	10		10.40	0.394		0.409
L	13		14	0.512		0.551
L1	3.50		3.93	0.138		0.155
L2	1.27		1.40	0.050		0.055

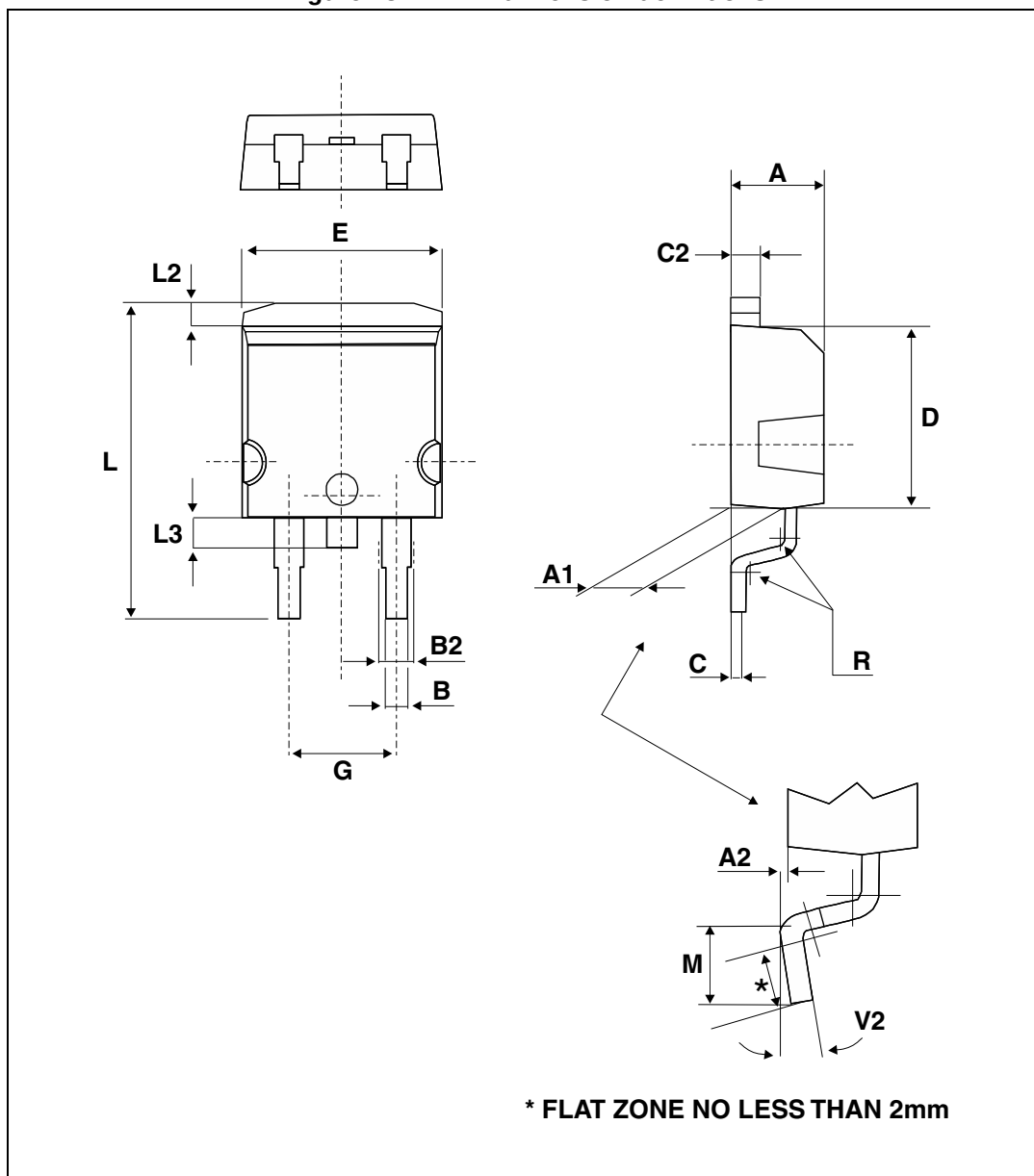
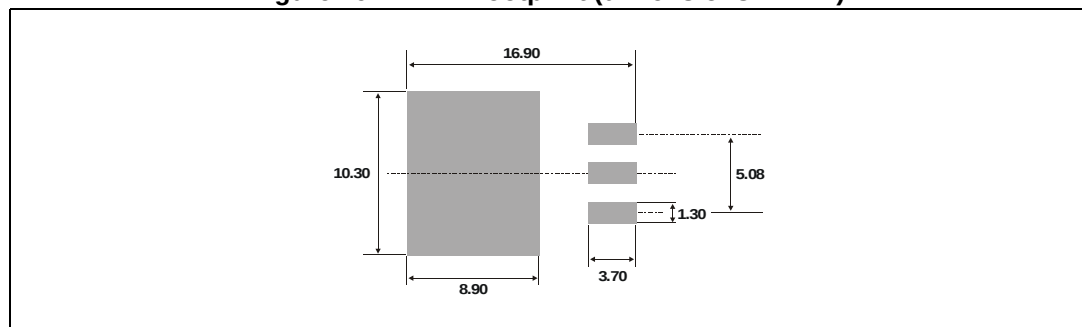
Figure 18. D²PAK dimension definitions

Table 10. D²PAK dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.70		0.93	0.027		0.037
B2	1.14		1.70	0.045		0.067
C	0.45		0.60	0.017		0.024
C2	1.23		1.36	0.048		0.054
D	8.95		9.35	0.352		0.368
E	10.00		10.40	0.393		0.409
G	4.88		5.28	0.192		0.208
L	15.00		15.85	0.590		0.624
L2	1.27		1.40	0.050		0.055
L3	1.40		1.75	0.055		0.069
M	2.40		3.20	0.094		0.126
R		0.40 typ.			0.016 typ.	
V2	0°		8°	0°		8°

Figure 19. D²PAK footprint (dimensions in mm)

3 Ordering information

Table 11. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH8R06D	STTH8R06D	TO-220AC	1.90 g	50	Tube
STTH8R06G	STTH8R06G	D ² PAK	1.48 g	50	Tube
STTH8R06G-TR	STTH8R06G	D ² PAK	1.48 g	1000	Tape and reel
STTH8R06FP	STTH8R06FP	TO-220FPAC	1.70 g	50	Tube
STTH8R06R	STTH8R06R	I ² PAK	1.5 g	50	Tube
STTH8R06DIRG	STTH8R06DI	TO-220AC Ins.	1.86 g	50	Tube

4 Revision history

Table 12. Document revision history

Date	Revision	Changes
May-2001	1	First issue
January-2002	2	D ² PAK and I ² PAK packages added
18-Oct-2004	3	TO-220AC Insulated package added
05-Dec-2004	4	D ² PAK foot print correction
10-Aug-2006	5	Reformatted to current standard. Added package insulation voltage data on page 1. Changed order code STTH8R06DI to STTH8R06DIRG.
16-Apr-2008	6	Reformatted to current standards. Corrected label for right hand curve in Figure 2 from T _j = 125 °C to T _j = 25 °C. Updated torque value recommendations and added ECOPACK statement in Section 2: Package information . Corrected order code in Table 11 .
22-Oct-2013	7	Updated Figure 7 .

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

ST PRODUCTS ARE NOT DESIGNED OR AUTHORIZED FOR USE IN: (A) SAFETY CRITICAL APPLICATIONS SUCH AS LIFE SUPPORTING, ACTIVE IMPLANTED DEVICES OR SYSTEMS WITH PRODUCT FUNCTIONAL SAFETY REQUIREMENTS; (B) AERONAUTIC APPLICATIONS; (C) AUTOMOTIVE APPLICATIONS OR ENVIRONMENTS, AND/OR (D) AEROSPACE APPLICATIONS OR ENVIRONMENTS. WHERE ST PRODUCTS ARE NOT DESIGNED FOR SUCH USE, THE PURCHASER SHALL USE PRODUCTS AT PURCHASER'S SOLE RISK, EVEN IF ST HAS BEEN INFORMED IN WRITING OF SUCH USAGE, UNLESS A PRODUCT IS EXPRESSLY DESIGNATED BY ST AS BEING INTENDED FOR "AUTOMOTIVE, AUTOMOTIVE SAFETY OR MEDICAL" INDUSTRY DOMAINS ACCORDING TO ST PRODUCT DESIGN SPECIFICATIONS. PRODUCTS FORMALLY ESCC, QML OR JAN QUALIFIED ARE DEEMED SUITABLE FOR USE IN AEROSPACE BY THE CORRESPONDING GOVERNMENTAL AGENCY.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2013 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

